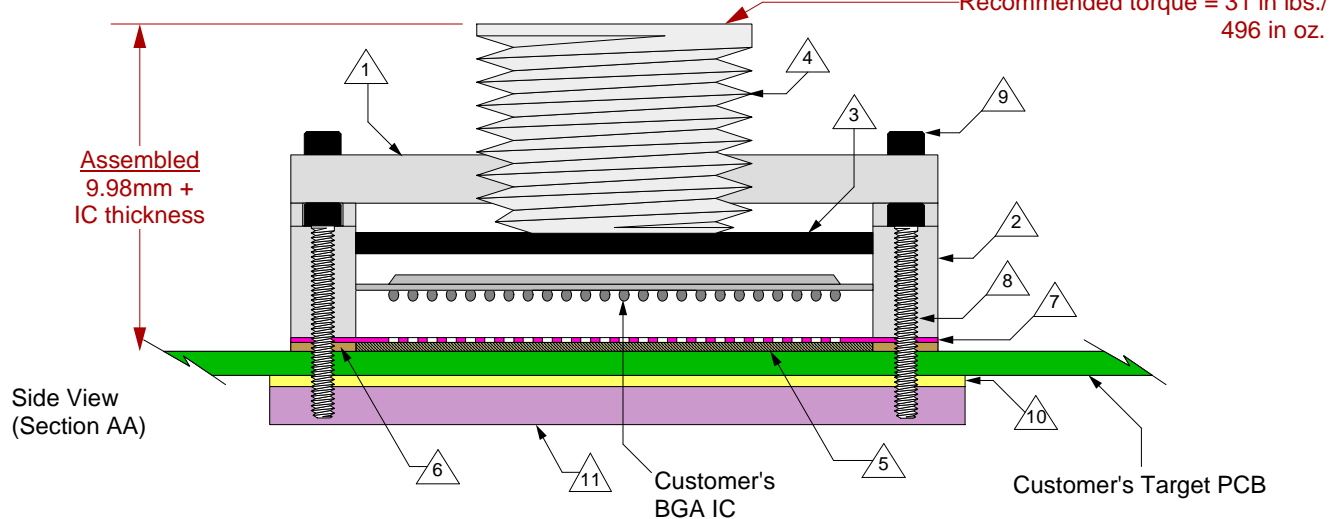
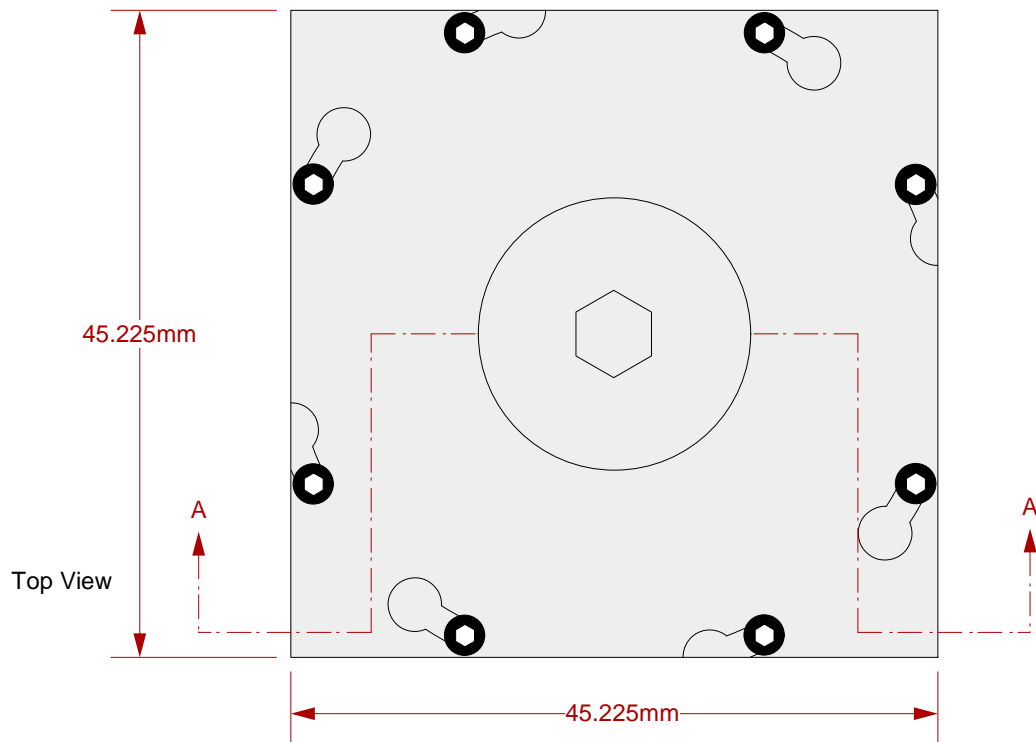


GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 7.5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 4.0mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.75mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, 1.59mm thick.
- 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-6049 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: H

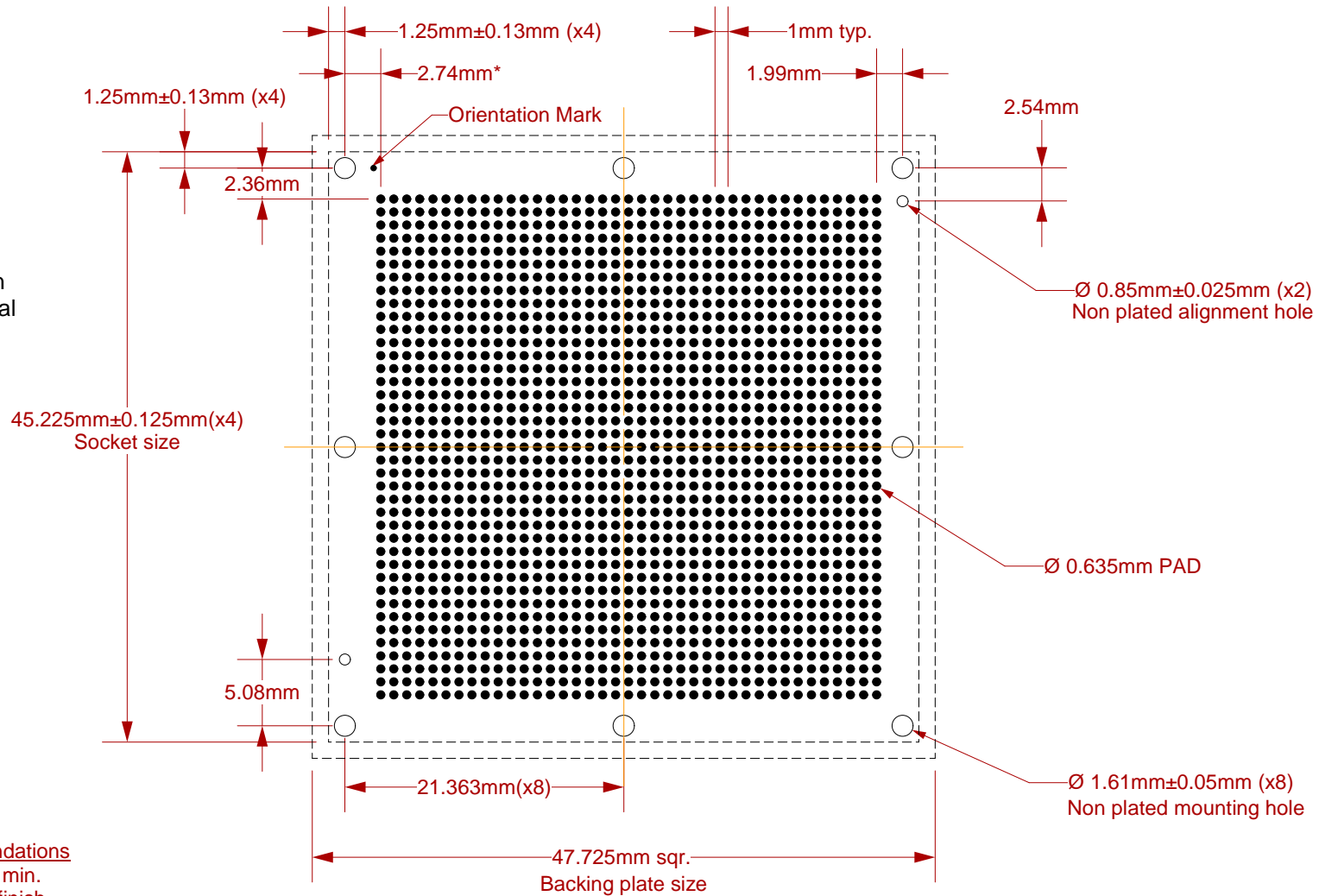
Drawing: H. Hansen

Date: 5/1/02

File: SG-BGA-6049 Dwg

Modified: 7/21/09, AE

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.




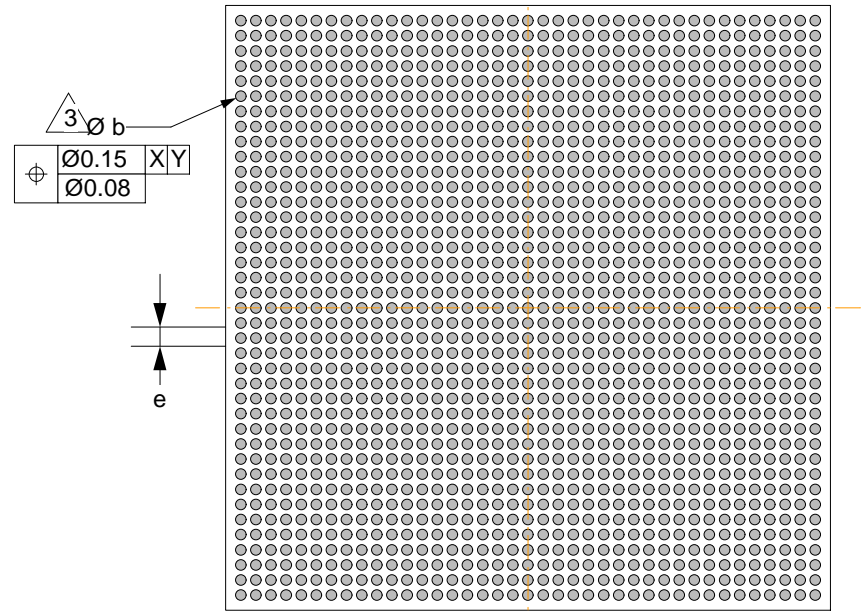
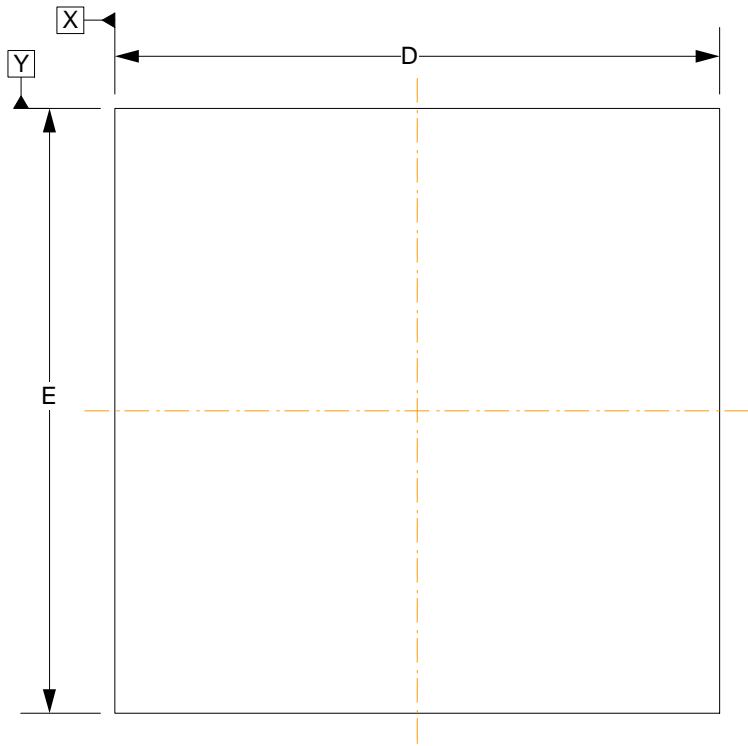
Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

Target PCB Recommendations
 Total thickness: 2.4mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

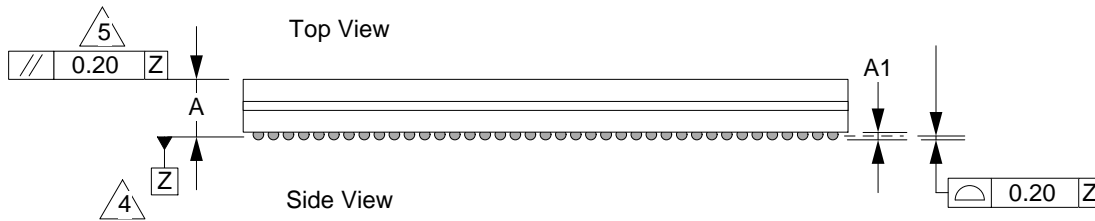
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SG-BGA-6049 Drawing</p>	<p>Status: Released</p>	<p>Scale: 2:1</p>	<p>Rev: H</p>
	<p>Drawing: H. Hansen</p>	<p>Date: 5/1/02</p>		
	<p>File: SG-BGA-6049 Dwg</p>	<p>Modified: 7/21/09, AE</p>		




Bottom View Array: 39x39



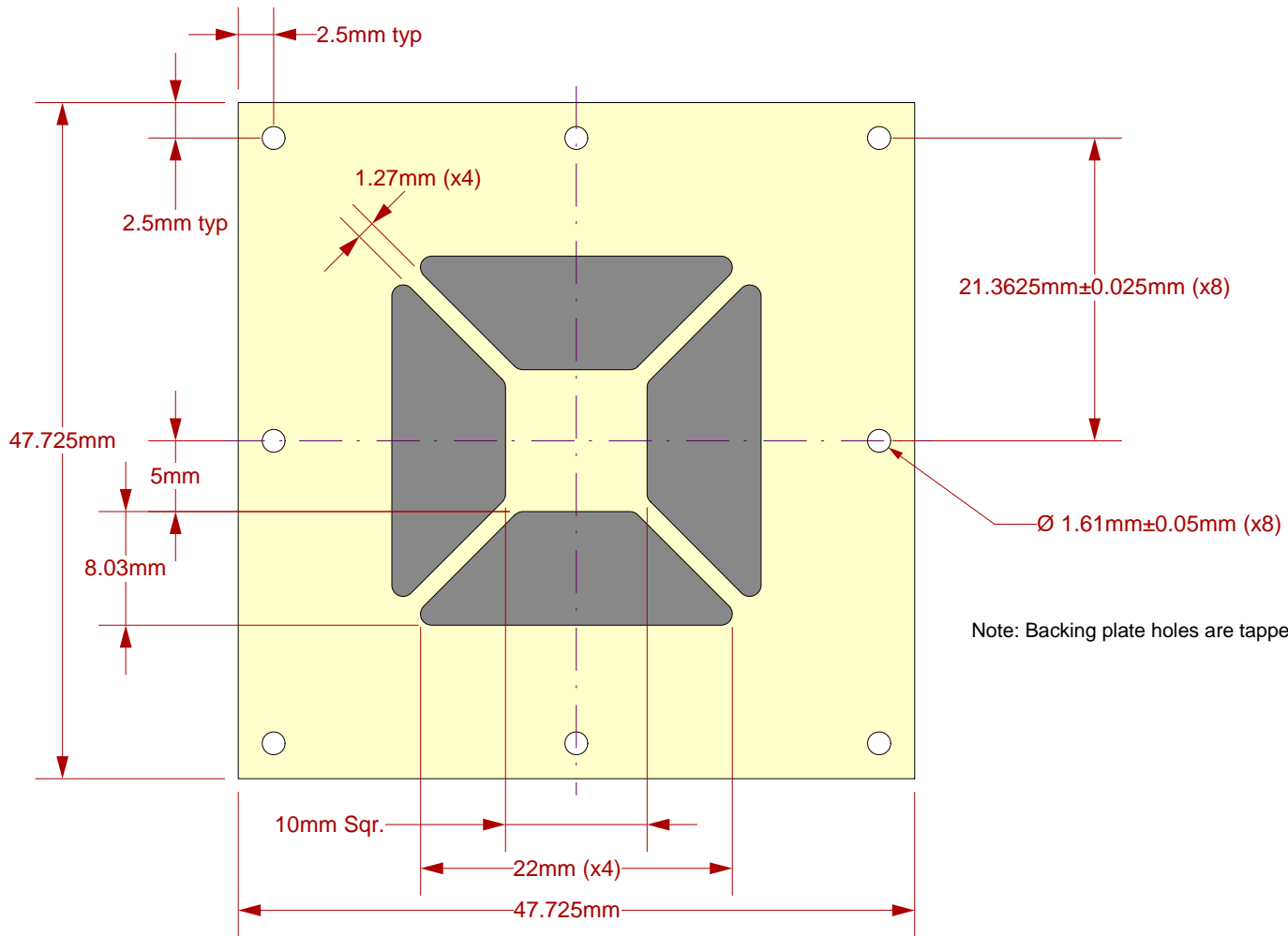
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
3. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 4. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.4	0.6
b		0.70
D	40.0 BSC	
E	40.0 BSC	
e	1.0 BSC	

Array: 39x39

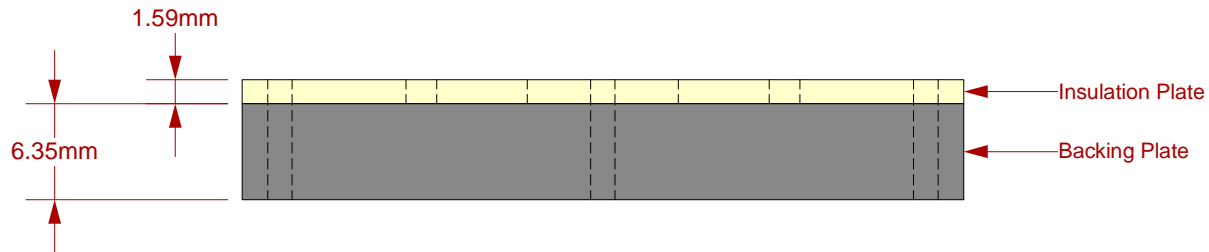
	SG-BGA-6049 Drawing	Status: Released	Scale: 2:1	Rev: H
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		File: SG-MGA-6049 Dwg	Modified: 7/21/09, AE	

Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Insulation Plate and Backing Plate

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		Drawing: H. Hansen	Date: 5/1/02	
		File: SG-MGA-6049 Dwg	Modified: 7/21/09, AE	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)